

## FEATURES

- | Low reverse leakage
- | High forward surge capability
- | High reliability
- | High temperature soldering guaranteed:260°C/10seconds



DO-214AC(SMA)



Schematic Symbol

## MECHANICAL DATA

- | Case:SMA Molded plastic
- | Epoxy: UL 94V-0 rate flame retardant
- | Lead: Pure tin plated, lead free

## APPROVALS

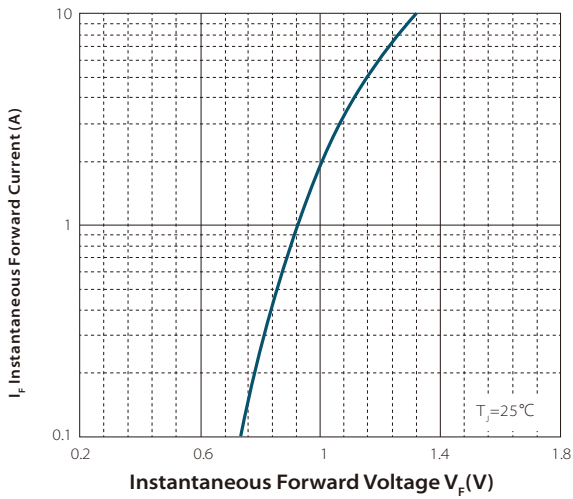
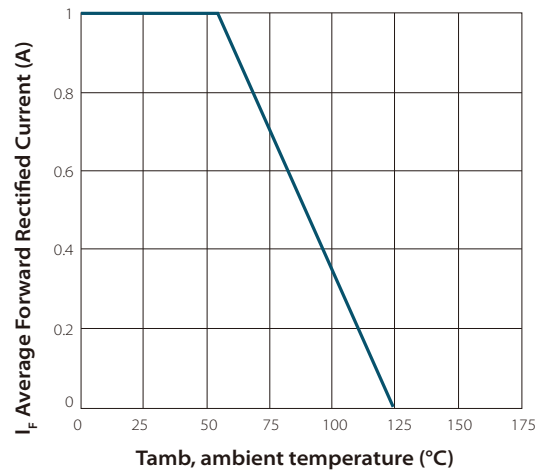
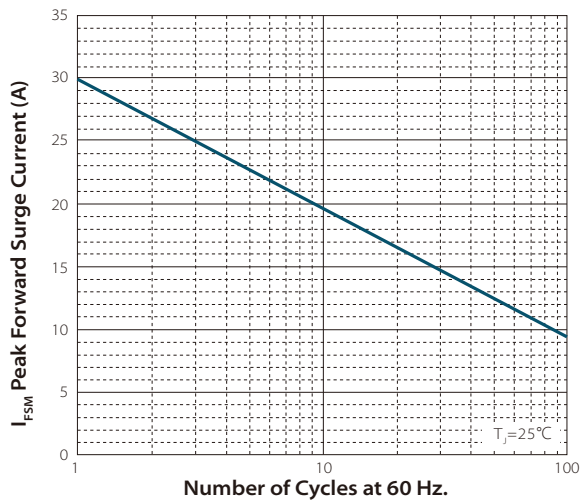
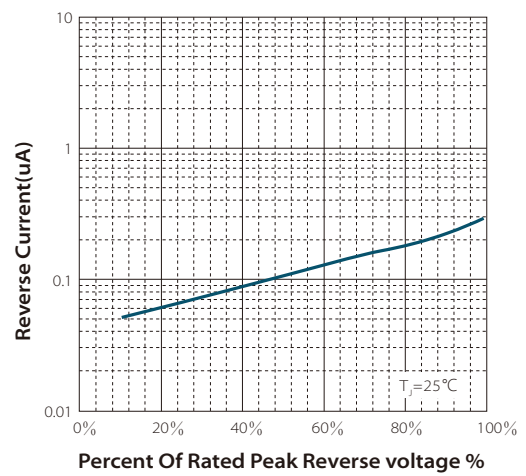
<b>RoHS</b>	Compliance with 2011/65/EU
<b>HF</b>	Compliance with IEC61249-2-21:2003

## MAXIMUM RATINGS AND CHARACTERISTICS (T<sub>A</sub>=25°C)

Symbol	Parameter	M1	M2	M3	M4	M5	M6	M7	Unit
	Marking	M1	M2	M3	M4	M5	M6	M7	
V <sub>RRM</sub>	Maximum repetitive peak reverse voltage	50	100	200	400	600	800	1000	V
V <sub>RMS</sub>	Maximum RMS voltage	35	70	140	280	420	560	700	
V <sub>DC</sub>	Maximum DC blocking voltage	50	100	200	400	600	800	1000	
I <sub>F(AV)</sub>	Maximum average forward rectified current	1.0							A
I <sub>FSM</sub>	Non-repetitive peak forward surge current 8.3 ms singlehalf sine-wave	30							
V <sub>F</sub>	Maximum forward voltage I <sub>F</sub> =1A	1.1							V
I <sub>R</sub>	Maximum reverse current @V <sub>DC</sub>	T <sub>A</sub> =25°C							uA
		T <sub>A</sub> =100°C							
R <sub>θJA</sub>	Typical thermal resistance (Note 1)	47							°C/W
C <sub>J</sub>	Type junction capacitance V <sub>R</sub> =4.0V,f=1MHz	65							PF
T <sub>J</sub>	Operating junction temperature rang	-55~+125							°C
T <sub>STG</sub>	Storage temperature rang	-55~+150							°C

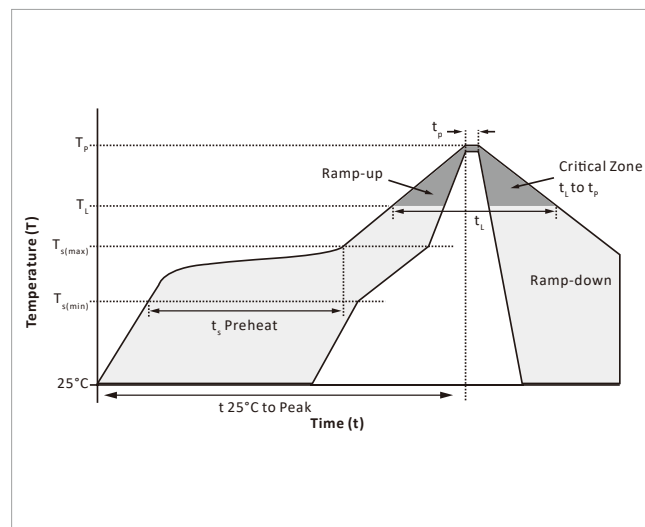
Note: 1) Thermal resistance from junction to ambient, PCB mounted.

# CHARACTERISTIC CURVES

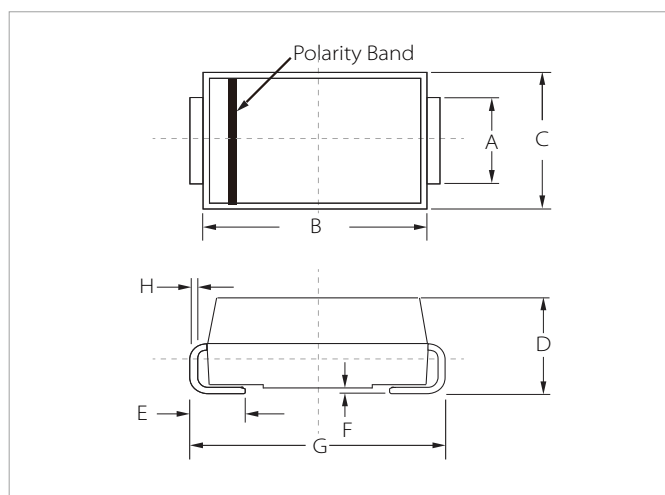
**Fig.1 Typical Forward Characteristic**

**Fig.2 Forward Current Derating Curve**

**Fig.3 Maximum Non Repetitive Peak Forward Surge Current**

**Fig.4 Typical Reverse Characteristics**


## SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ( $T_{s(min)}$ )	150°C
	Temperature Max ( $T_{s(max)}$ )	200°C
	Time (min to max) ( $t_p$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time (min to max) ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260°C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C

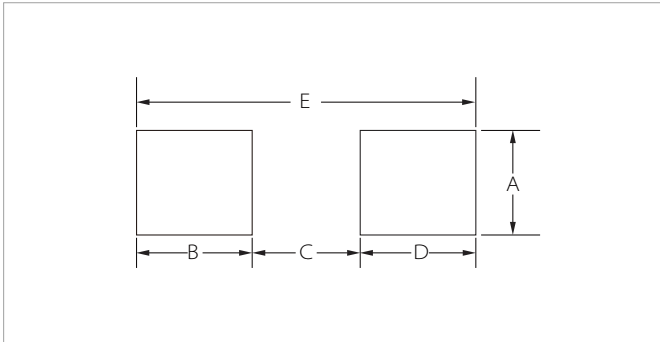


## DO-214AC(SMA) PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.20	1.60	0.047	0.063
B	4.20	4.60	0.165	0.181
C	2.60	2.80	0.102	0.110
D	2.10	2.40	0.083	0.094
E	0.76	1.52	0.030	0.060
F	0.02	0.20	0.001	0.008
G	4.85	5.25	0.191	0.207
H	0.15	0.30	0.006	0.012

## RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.63	-	0.064	-
B	1.45	-	0.057	-
C	-	2.80	-	0.090
D	1.45	-	0.057	-
E	5.28REF		0.208REF	

## ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
M1~M7	DO-214AC(SMA)	7500PCS	13"

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